



**Materials Declaration**

<b>Package</b>	Sidebrazed
<b>Body Size</b>	300 mils
<b>Lead Count</b>	20
<b>Option</b>	Au

Combolid			
Item	% of Combolid	Weight (g)	PPM
Kovar	92	2.76E-01	169211
Nickel	4	1.20E-02	7357
Gold	4	1.20E-02	7357
<b>Subtotal</b>		<b>3.00E-01</b>	<b>183925</b>

Lid Frame			
Item	% of Lid Frame	Weight (g)	PPM
Gold	79.58	2.55 E-02	15613
Sn	20.42	6.53 E-03	4006
<b>Subtotal</b>		<b>3.20 E-02</b>	<b>19619</b>

Ceramic Package			
Item	% of Ceramic	Weight (g)	PPM
Ceramic			
Al2O3	90.5	8.51 E-01	521550
Cr2O3	3.9	3.67 E-02	22476
SiO2	3.5	3.29 E-02	20170
TiO2	1.0	9.40 E-03	5763
CaO	0.6	5.64 E-03	3458
MgO	0.5	4.70 E-03	2881
<b>Subtotal</b>		<b>9.40 E-01</b>	<b>576298</b>

Metallization			
Item	% of Metallization	Weight (g)	PPM
Tungsten	96.61	4.83 E-02	29615
Molybdenum	3.39	1.70 E-03	1039
<b>Subtotal</b>		<b>5.00 E-02</b>	<b>30654</b>

Lead			
Item	% of Lead	Weight (g)	PPM
Iron	58	1.51 E-01	92453
Nickel	40.7	1.06 E-01	64876
Manganese	0.8	2.08 E-03	1275
Cobalt	0.5	1.30 E-03	797
<b>Subtotal</b>		<b>2.60 E-01</b>	<b>159402</b>

Ag-Cu ( base metal)			
Item	% of Ag-Cu	Weight (g)	PPM
Silver	85	8.50 E-03	5211
Copper	15	1.50 E-03	920
<b>Subtotal</b>		<b>1.00 E-02</b>	<b>6131</b>

Nickel Plating ( 1st coating)			
Item	% of Nickel Plating	Weight (g)	PPM
Nickel	93.89	9.39 E-03	5756
Palladium	5.36	5.36 E-04	329
Boron	0.7	7.00 E-05	43
Lead	0.05	5.00 E-06	3
<b>Subtotal</b>		<b>1.00 E-02</b>	<b>6131</b>

Nickel Plating ( 2nd layer)			
Item	% of Nickel Plating	Weight (g)	PPM
Nickel	92	9.20 E-03	5640
Cobalt	8	8.00 E-04	490
<b>Subtotal</b>		<b>1.00 E-02</b>	<b>6131</b>

External Leadframe Plating			
Item	% of External Plating	Weight (g)	PPM
Gold	100	1.00 E-02	6131

Bond Wires			
Item	% of Wire	Weight (g)	PPM
Aluminum	100	1.20 E-03	736

Chip 1			
Item	% of Chip	Weight (g)	PPM
Si	100	6.70 E-03	4108

Die Attach Paste			
Item	% of Die Attach Paste	Weight (g)	PPM
Silver Filler	80	9.60 E-04	589
Cyanate ester resin	20	2.40 E-04	147
<b>Subtotal</b>		<b>1.20 E-03</b>	<b>736</b>

Package Totals	
Weight (g)	PPM
<b>1.63E+00</b>	<b>1000000</b>

Note: The information provided in this declaration are true to the best of ADI's knowledge. ADI derived most of the information listed in this declaration from documents provided by third parties, and assumes no liability to any inaccuracy of such information.



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<b>Package</b>	Sidebrazed
<b>Body Size</b>	300 mils
<b>Lead Count</b>	20
<b>Option</b>	SnPb

### Comolid

Item	% of Comolid	Weight (g)	PPM
Kovar	92	1.43E-01	74116
Nickel	4	6.20E-03	3222
Gold	4	6.20E-03	3222
Subtotal		1.55E-01	80561

### Lid Frame

Item	% of Lid Frame	Weight (g)	PPM
Gold	79.58	2.55 E-02	13236
Sn	20.42	6.53 E-03	3396
Subtotal		3.20 E-02	16632

### Ceramic Package

Item	% of Ceramic	Weight (g)	PPM
Al2O3	77.0	1.29 E+00	668347
Iron	6.3	1.05 E-01	54770
Nickel	4.9	8.12 E-02	42184
Cr2O3	3.3	5.53 E-02	28730
SiO2	3.0	5.04 E-02	26213
Co,Ag,Cu,MgO,CaO	2.9	4.81 E-02	24998
Tungsten	2.5	4.18 E-02	21700
Gold	0.2	2.67 E-03	1389
Subtotal		1.67 E+00	867983

### Bond Wires

Item	% of Wire	Weight (g)	PPM
Aluminum	100	1.00 E-02	5198

### Chip

Item	% of Chip	Weight (g)	PPM
Si	100	8.00 E-03	4158

### External Leadframe Plating

Item	% of Plating	Weight (g)	PPM
Tin	63	1.83 E-02	9496
Lead	37	1.07 E-02	5577
Subtotal		2.90 E-02	15073

### Die Attach Paste

Item	% of Die Attach Paste	Weight (g)	PPM
Silver Filler	80	1.60 E-02	8316
Cyanate ester resin	20	4.00 E-03	2079
Subtotal		2.00 E-02	10395

### Package Totals

Weight (g)	PPM
<b>1.92E+00</b>	<b>1000000</b>

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